

1 1. A package for an integrated circuit chip adapted
2 to operate at microwave frequencies, comprising:
3 an electrically conductive lead frame having
4 electrical leads extending outwardly from an inner region;
5 a base section adhesively affixed to a bottom
6 surface portion of the lead frame, portions of the
7 electrical leads extending outwardly from the base section;
8 a plastic cover; and
9 wherein the base section and the cover are
10 configured to provide a cavity when the cover and the base
11 section are affixed with the integrated circuit chip being
12 encapsulated within the provided cavity.

1 2. The package recited in claim 1 wherein the base
2 section comprises a dielectric member.

1 3. The package recited in claim 2 wherein the base
2 section includes a conductive member affixed to the
3 dielectric member.

1 4. The package recited in claim 1 wherein the cover
2 has a recess disposed within sidewalls and wherein ends of
3 the sidewalls are affixed to the base section.

1 5. The package recited in claim 1 wherein the cover
2 is configured to increase surface tension with an adhesive
3 disposed between the cover and the lead frame.

1 6. The package recited in claim 5 wherein the cover
2 is configured with a ridge to increase the surface tension.

1 7. The package recited in claim 1 wherein the base
2 section is configured to increase surface tension with an

3 adhesive disposed between the base section and the lead
4 frame.

1 8. The package recited in claim 7 wherein the base
2 section is configured with a ridge to increase the surface
3 tension.

1 9. The package recited in claim 6 wherein the
2 adhesive projects towards an interior of the package a
3 distance in the order of 1% of the width of an exterior
4 length of the package.

1 10. The package recited in claim 8 wherein the
2 adhesive projects towards an interior of the package a
3 distance in the order of 1% of the width of an exterior
4 length of the package.

1 11. A method for packaging an integrated circuit
2 chip adapted to operate at microwave frequencies, comprising
3 the steps of:

4 providing a lead frame having: electrical leads
5 extending outwardly from an inner region of the lead frame;
6 adhesively affixing a base section to the lead
7 frame with portions of the electrical leads extending
8 outwardly from the base;

9 connecting electrical wires between the
10 integrated circuit chip and the electrical leads; and

11 affixing a cover to provide the package with
12 such integrated circuit chip being disposed within a cavity
13 formed by affixed cover and base section.

12. A method for packaging an integrated circuit chip adapted to operate at microwave frequencies, comprising the steps of:

providing a lead frame having a plurality of sites therein, each site having: electrical leads extending outwardly from an inner region of the site;

adhesively affixing each one of a plurality of plastic base section over a corresponding one of the site;

connecting electrical wires between the integrated circuit chip at each one of the plurality of sites and the electrical leads at the corresponding one of the sites; and

adhesively affixing covers to encapsulate each one of the integrated circuits and the electrical wires connected thereto within a cavity formed by the corresponding one of the plurality of the affixed corresponding one of the covers.

13. A package for an integrated circuit chip adapted to operate at microwave frequencies, comprising:
an electrically conductive lead frame having electrical leads adapted for electrical connection to the integrated circuit;

a base section having;

a dielectric member;

a conductive member;

wherein the dielectric member has an

aperture disposed in registration with an inner region of the lead frame and the conductive member has one upper

portion thereof adhesively affixed to a bottom portion of the

dielectric member and another upper portion electrically

connected to a bottom ground plane conductor of the

15 integrated circuit, such integrated circuit chip being
16 disposed in registration with the aperture;
17 wherein the dielectric member is disposed
18 between the lead frame and the conductive member;
19 a plastic cover; and
20 wherein the base section and the cover are
21 configured to provide a cavity when the cover and the base
22 section are affixed with the integrated circuit chip being
23 disposed with such provided cavity and with a bottom surface
24 portion of the conductive member being exposed exteriorly of
25 the package.

1 14. A method for packaging an integrated circuit
2 chip adapted to operate at microwave frequencies, comprising
3 the steps of:

4 providing a lead frame having electrical leads
5 extending outwardly from an interior region of the lead
6 frame;

7 electrically connecting a conductive member of
8 a base section to a bottom ground plane conductor of the
9 integrated circuit with an apertured dielectric disposed
10 between the lead frame and the conductive member and the
11 aperture in registration with the integrated circuit chip;

12 connecting electrical wires between the
13 integrated circuit chip and the electrical leads;

14 affixing a plastic cover to provide a package
15 for the integrated circuit chip with such integrated circuit
16 chip being disposed within a cavity formed by the affixed
17 cover and with a portion of the electrically conductive
18 member being exposed exteriorly of the package.

14 circuit chip when the base section and the cover are affixed
15 and to expose a bottom portion of the conductive member
16 exteriorly of the package.